



**Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise specified)**

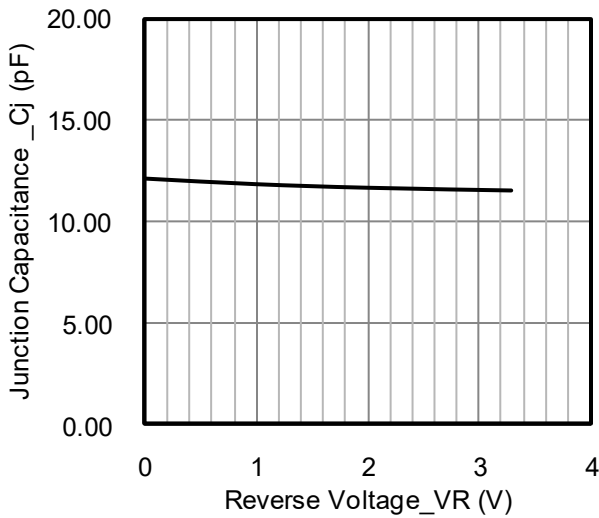
Parameter	Symbol	Value	Unit
Peak Pulse Power(8/20μs)	Ppk	1800	W
Peak Pulse Current(8/20μs)	I <sub>PP</sub>	100	A
ESD per IEC 61000-4-2 (Air)	V <sub>ESD</sub>	±30	kV
ESD per IEC 61000-4-2 (Contact)		±30	
Operating Temperature Range	T <sub>J</sub>	-40 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to +150	°C

**Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise specified)**

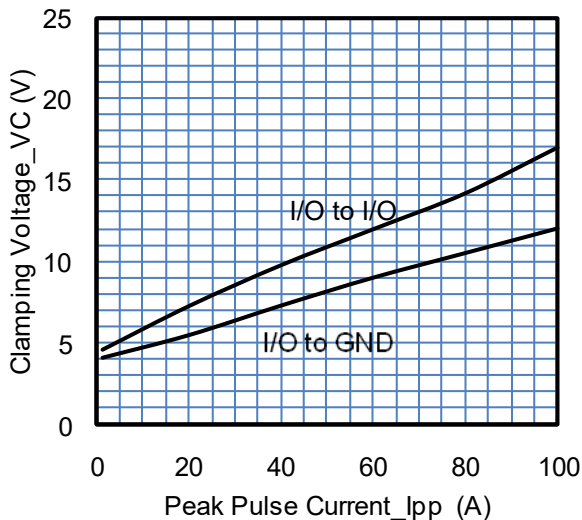
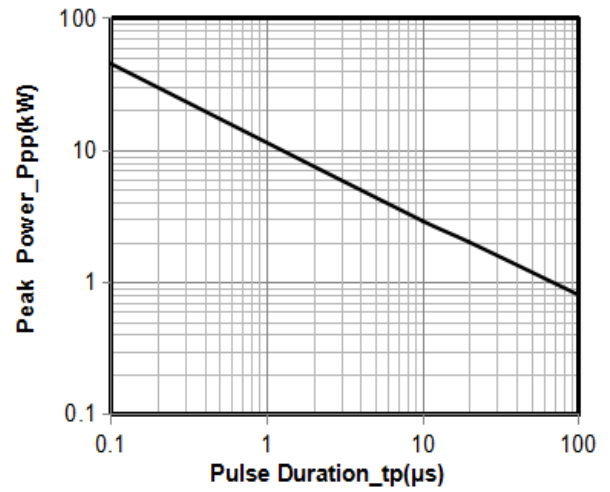
Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V <sub>RWM</sub>			3.3	V	
Punch-Through Voltage	V <sub>PT</sub>	3.5			V	I <sub>T</sub> = 2μA
Snap-Back Voltage	V <sub>SB</sub>	2.8			V	I <sub>T</sub> = 50mA
Reverse Leakage Current	I <sub>R</sub>			0.5	μA	V <sub>RWM</sub> = 3.3V
Clamping Voltage	V <sub>C</sub>			11	V	I <sub>PP</sub> = 50A (8 x 20μs pulse), any I/O pin to ground
Clamping Voltage	V <sub>C</sub>			13	V	I <sub>PP</sub> = 50A (8 x 20μs pulse), between I/O pins
Clamping Voltage	V <sub>C</sub>			15	V	I <sub>PP</sub> = 100A (8 x 20μs pulse), any I/O pin to ground
Clamping Voltage	V <sub>C</sub>			18	V	I <sub>PP</sub> = 100A (8 x 20μs pulse), between I/O pins
Junction Capacitance	C <sub>J</sub>		16	25	pF	V <sub>R</sub> = 0V, f = 1MHz, between I/O pins and ground
Junction Capacitance	C <sub>J</sub>		8	12	pF	V <sub>R</sub> = 0V, f = 1MHz, between I/O pins

Note 1: I/O pins are Pin 1, 4, 5 and 8

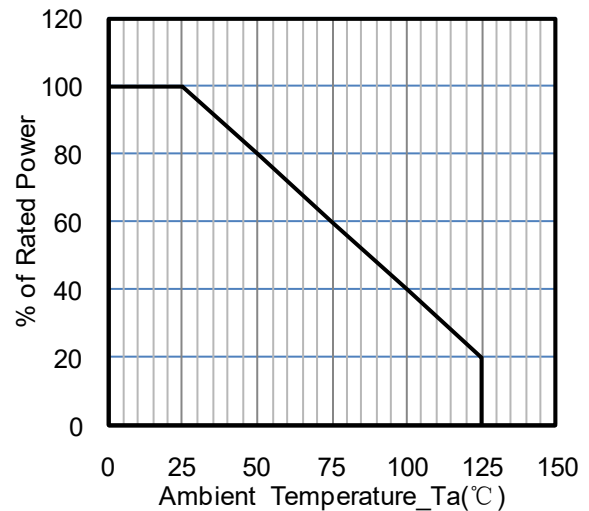
**Typical Performance Characteristics (TA=25°C unless otherwise Specified)**



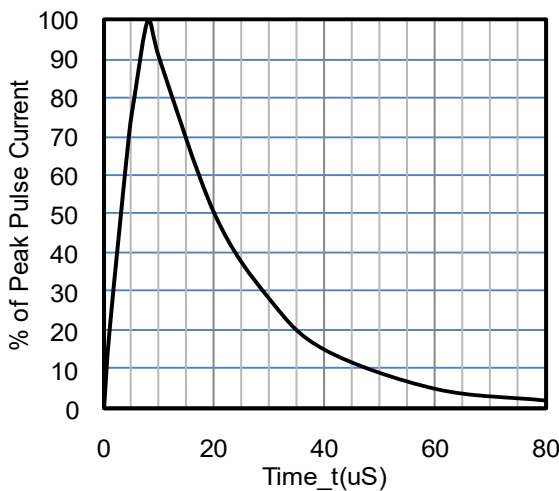
**Junction Capacitance vs. Reverse Voltage**



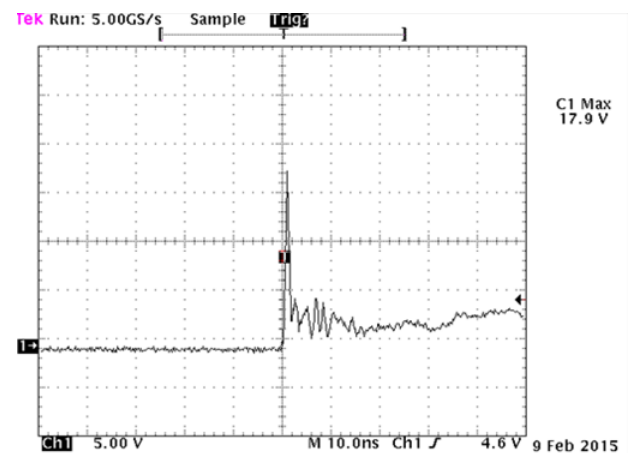
**Clamping Voltage vs. Peak Pulse Current**



**Power Derating Curve**



**8 X 20μs Pulse Waveform**



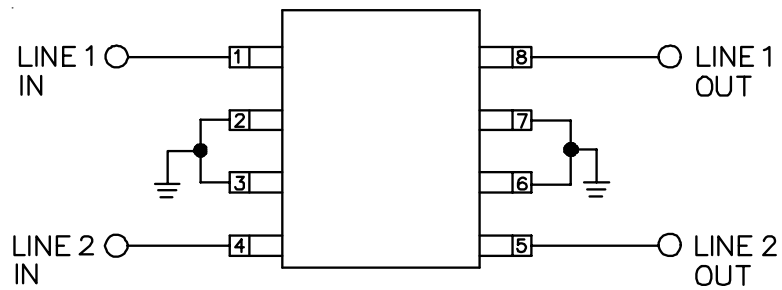
**Note: Data is taken with a 10x attenuator**

**ESD Clamping Voltage**

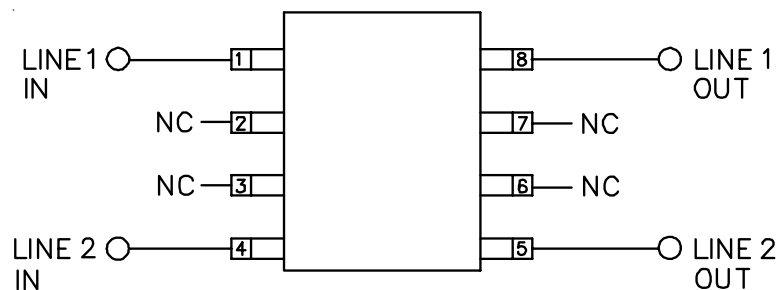
**+8 kV Contact per IEC61000-4-2**

## Typical Applications

The LC03-3.3 is designed to protect two high speed data lines (one differential pair) from transient over-voltages which result from lightning and ESD. The device can be configured to protect in differential (Line to Line) and common (Line to Ground) mode. Data line inputs/outputs are connected at pins 1 to 8, and 4 to 5 as shown below. Pins 2, 3, 6, 7 are connected to ground. These pins should be connected directly to a ground plane on the board for the best results, the path length is kept as short as possible to minimize parasitic inductance. In applications where high common voltages are present, differential protection is achieved by leaving pins 2, 3, 6, and 7 not connected.

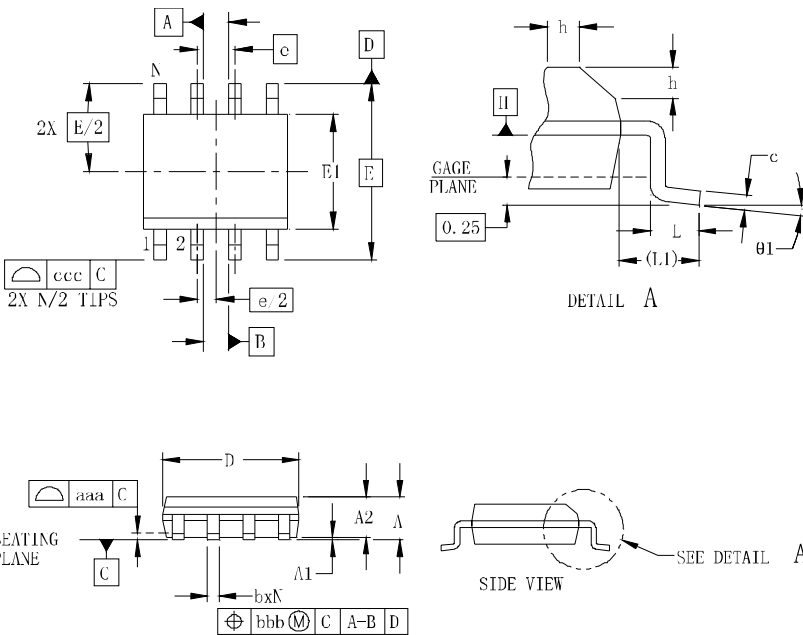


**Connection for differential (Line to Line) and common mode protection (Line to Ground)**



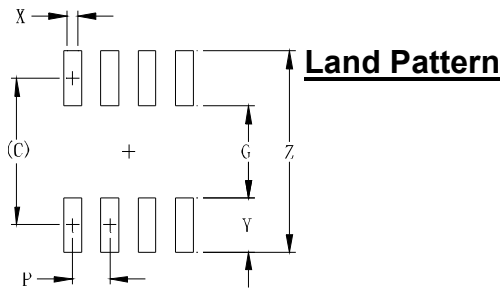
**Connection for differential protection (Line to Line)**

**SO-8 Package Outline Drawing**



SYM	DIMENSIONS					
	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.35		1.75	0.053		0.069
A1	0.10		0.25	0.004		0.010
A2	1.25		1.65	0.049		0.065
b	0.31		0.51	0.012		0.020
c	0.17		0.25	0.007		0.010
D	4.80	4.90	5.00	0.189	0.193	0.197
E	6.00 BSC			0.236 BSC		
e	1.27 BSC			0.050 BSC		
h	0.25		0.50	0.010		0.020
L	0.40	0.72	1.04	0.016	0.028	0.041
L1	(1.04)			(0.041)		
N	8			8		
theta1	0°		8°	0°		8°
aaa	0.10			0.004		
bbb	0.25			0.010		
ccc	0.20			0.008		

**Suggested**



SYM	DIMENSIONS	
	MILLIMETERS	INCHES
C	(5.20)	0.205
G	3.00	0.118
P	1.27	0.050
X	0.60	0.024
Y	2.20	0.087
Z	7.40	0.291